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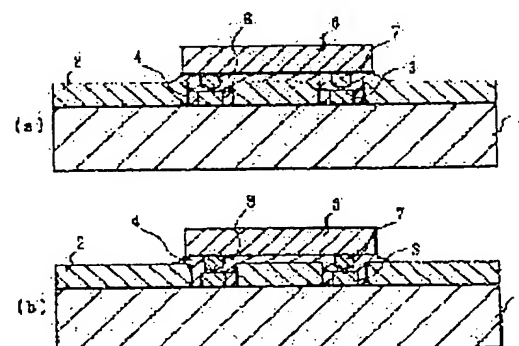
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(54) FLIP CHIP MOUNTING METHOD

(57)Abstract:

PURPOSE: To provide high-reliability sealing resin which never causes voids in grooves of an insulation film such as solder resist having pads for mounting parts on a circuit board.

CONSTITUTION: Sealing resin a4 is charged in grooves of an insulation film 2 having mounting pads 3 for a circuit board 1. Heating plus vacuum defoaming or ultrasonic vibration is applied in this condition to remove foams round the pads 3 and sealing resin b8 for the desired portion is more fed to mount a semiconductor element 6.



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